



S1MWF

Product Summary (@ T_A = +25°C)

		-			
V _{RRM} (V) I _O (A)		V _F (MAX) (V)	Ι _{R(MAX)} (μΑ)		
1000	1	1.1	5		

Description and Applications

The S1MWF is a rectifier packaged in the small form factor, low profile SOD123F (Type B) package. Providing high reverse breakage voltage, low reverse leakage current, and high surge current capability for standard rectification, this device is ideal for use in general rectification applications such as:

- Switching Mode Power Supplies
- DC-DC Converters
- AC-DC Adaptors/Chargers
- Mobile Devices
- LED Lighting



Top View

SOD123F (Type B)

1 O 2 CATHODE ANODE

1.0A SURFACE MOUNT GLASS PASSIVATED RECTIFIER

Lead-Free Finish & RoHS Compliant (Notes 1 & 2) Halogen and Antimony Free. "Green" Device (Note 3)

Case Material: Molded Plastic, "Green" Molding Compound;

Terminals: Matte Tin Finish Annealed over Copper Leadframe.

UL Flammability Classification Rating 94V-0

Moisture Sensitivity: Level 1 per J-STD-020

Weight: 0.018 grams (Approximate)

Solderable per MIL-STD-202, Method 208 (e3)

Features and Benefits

Mechanical Data

Case: SOD123F (Type B)

Polarity: Cathode Band

Glass Passivated Die Construction Small Form Factor, Low Profile Surge Overload Rating to 30A Peak Low Reverse Leakage Current High Reverse Breakage Voltage

Schematic View

Ordering Information (Note 4)

Part Number	Compliance	Case	Packaging
S1MWF-7	Commercial	SOD123F (Type B)	3,000/Tape & Reel

Bottom View

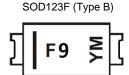
Notes: 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.

2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



 $\begin{array}{l} \mathsf{F9} = \mathsf{Product Type Marking Code} \\ \mathsf{YM} = \mathsf{Date Code Marking} \\ \mathsf{Y} = \mathsf{Year} \ (\mathsf{ex: D} = 2016) \\ \mathsf{M} = \mathsf{Month} \ (\mathsf{ex: 9} = \mathsf{September}) \end{array}$

Date Code Key

Year		2014	2015	20	016	2017	201	8	2019	2020		2021
Code		В	С		D	E	F		G	Н		I
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	Ν	D



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitive load, derate current by 20%.				
Characteristic			Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage		V _{RRM} V _{RWM} V _{RM}	1,000	V
RMS Reverse Voltage		V _{R(RMS)}	700	V
Average Rectified Output Current	@ T _T = +100°C	Ιo	1.0	A
Non-Repetitive Peak Forward Surge Curren 8.3ms Single Half Sine-Wave Superimposed		I _{FSM}	30	А

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance, Junction to Case (Note 5)	$R_{ ext{ heta}JC}$	8	°C/W
Typical Thermal Resistance Junction to Ambient (Note 5)	$R_{ ext{ heta}JA}$	56	°C/W
Operating and Storage Temperature Range	TJ, TSTG	-55 to +150	°C

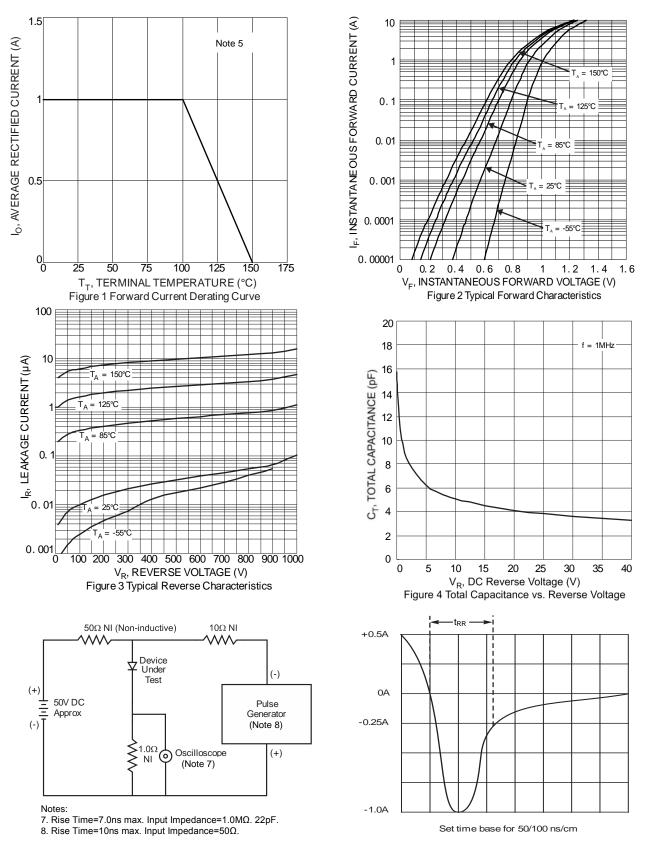
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

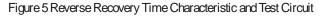
Characteristic	Symbol	Symbol Min T		Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 6)	V _{(BR)R}	1,000	—	—	V	$I_R = 5\mu A$
Forward Voltage Drop	VF	_	0.95 0.85 1.0 0.9	1.1 1.0 —	V	$I_{F} = 1A, T_{J} = +25^{\circ}C$ $I_{F} = 1A, T_{J} = +125^{\circ}C$ $I_{F} = 2A, T_{J} = +25^{\circ}C$ $I_{F} = 2A, T_{J} = +125^{\circ}C$
Leakage Current (Note 6)	I _R	—	0.15 6	5.0 100	μΑ	$V_R = 1,000V, T_J = +25^{\circ}C$ $V_R = 1,000V, T_J = +125^{\circ}C$
Reverse Recovery Time	t _{RR}	_	1.5	3.0	μs	I _F = 0.5A, I _R = 1.0A, I _{RR} = 0.25A
Total Capacitance	CT	—	7	—	pF	$V_R = 4.0V_{DC}$, f = 1MHz

 Notes:
 5. Device mounted on FR-4 substrate, 1.0" x 1.0", 2oz, single-sided, PC boards with 0.2" x 0.25" copper pad.

 6. Short duration pulse test used to minimize self-heating effect.



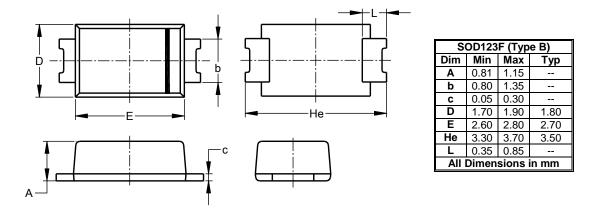






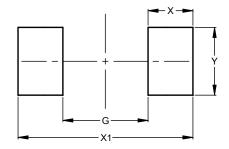
Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.



Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



Dimensions	Value (in mm)
G	1.90
Х	1.00
X1	3.90
Y	1.50



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